IN THE CLAIMS:

Claim 1 (currently amended): A laminated ceramic substrate formed by laminating a plurality of ceramic layers ~~each having a circuit element pattern formed on a surface thereof~~, the laminated ceramic substrate ~~further~~ including a side electrode comprising a side edge electrode layer formed on a side edge portion of ~~each~~ at least one of the ceramic ~~layer~~ layers which overlaps with and connects to a side edge electrode layer formed on a side edge portion of ~~another~~ an adjacent ceramic layer directly above and/or directly below ~~an adjacent~~ the at least one ceramic layer, each side edge electrode layer ~~positioned~~ being within a through hole in the ceramic substrate, the through hole ~~bounded~~ defined by a side surface of the laminated ceramic substrate, a wall approximately parallel to the side surface of the laminated ceramic substrate and two perpendicular walls approximately perpendicular to the side surface of the laminated ceramic substrate, a length La of the parallel wall and a depth Lb of the parallel wall from the side surface of the laminated ceramic substrate having a relationship of La > Lb.

Claim 2 (previously presented): A laminated ceramic substrate according to claim 1, wherein each perpendicular wall is connected to the parallel wall by a corner portion with a circular-arc shape of a radius R in which R is greater than 0.02 mm.

Claim 3-20 (canceled):

Claim 21 (currently amended): A laminated ceramic substrate formed by laminating a plurality of ceramic layers ~~each having a circuit element pattern formed on a surface thereof~~, the

laminated ceramic substrate ~~further~~ including opposite side electrodes each comprising a side edge electrode layer formed on a side edge portion of ~~each~~ at least one of ceramic ~~layer within~~ layers which overlaps with and connects to a side edge electrode layer formed on a side edge portion of ~~another~~ an adjacent ceramic layer directly above and/or directly below ~~an adjacent~~ the at least one ceramic layer, each side edge electrode layer ~~positioned~~ being within a through hole in the ceramic substrate, the through hole ~~bounded~~ defined by a side surface of the laminated ceramic substrate, a wall approximately parallel to the side surface of the laminated ceramic substrate and two perpendicular walls approximately perpendicular to the side surface of the laminated ceramic substrate, a length La of the parallel wall and a depth Lb of the parallel wall from the side surface of the laminated ceramic substrate having a relationship of La > Lb.

Claim 22 (previously presented): A laminated ceramic substrate according to claim 21, wherein each perpendicular wall is connected to the parallel wall by a corner portion with a circular-arc shape of a radius R in which R is greater than 0.02 mm.

Claim 23 (currently amended): A laminated ceramic substrate according to claim 21, wherein the ~~depth~~ amount of the depths (LbL + LbR) of opposite side edge electrode layers on at least one ceramic layer differs from the ~~depth~~ amount of the depths (LbL + LbR) of opposite side edge electrode layers on the other ceramic layers.

Claim 24 (currently amended): A laminated ceramic substrate according to claim 22, wherein the ~~depth~~ amount of the depths (LbL + LbR) of opposite side edge electrode layers on at least one ceramic layer differs from the ~~depth~~ amount of the depths (LbL + LbR) of opposite side

edge electrode layers on the other ceramic layers.